

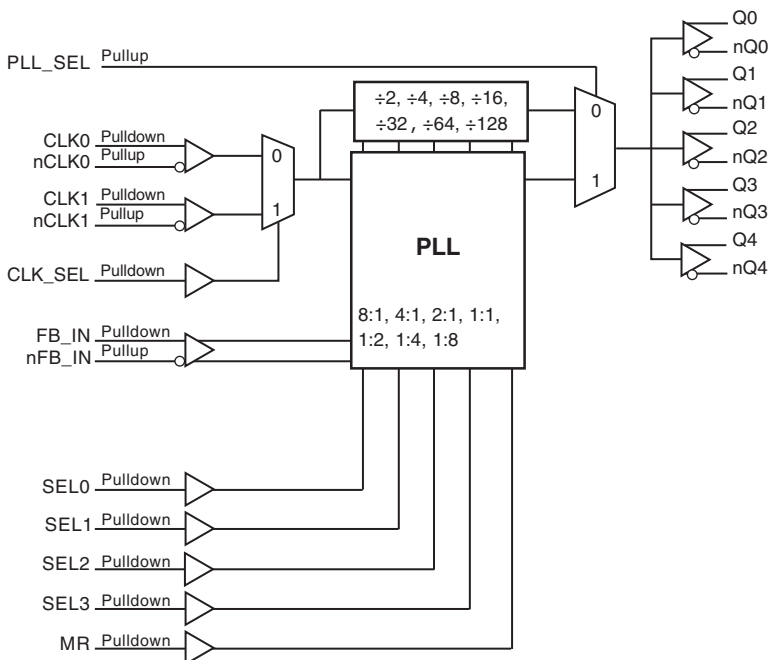
General Description

The 8735-31 is a highly versatile 1:5 Differential -to-3.3V LVPECL Clock Generator. The 8735-31 has a fully integrated PLL and can be configured as zero delay buffer, multiplier or divider, and has an output frequency range of 15.625MHz to 350MHz. The reference divider, feedback divider and output divider are each programmable, thereby allowing for the following output-to-input frequency ratios: 8:1, 4:1, 2:1, 1:1, 1:2, 1:4, 1:8. The external feedback allows the device to achieve “zero delay” between the input clock and the output clocks. The PLL_SEL pin can be used to bypass the PLL for system test and debug purposes. In bypass mode, the reference clock is routed around the PLL and into the internal output dividers.

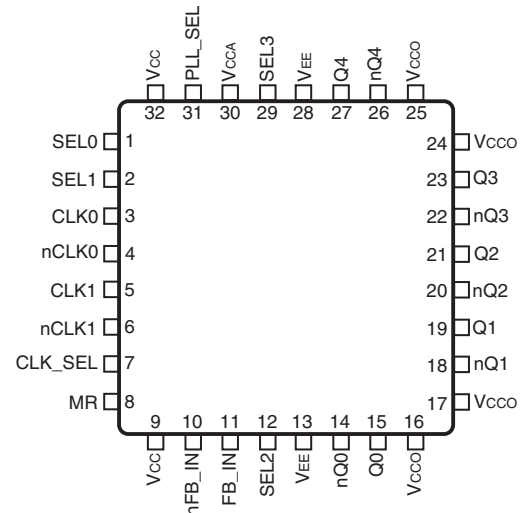
Features

- Five differential 3.3V LVPECL output pairs
- Selectable differential clock inputs
- CLKx/nCLKx pairs can accept the following differential input levels: LVPECL, LVDS, LVHSTL, HCSL, SSTL
- Output frequency range: 15.625MHz to 350MHz
- Input frequency range: 15.625MHz to 350MHz
- VCO range: 250MHz to 700MHz
- External feedback for “zero delay” clock regeneration with configurable frequencies
- Programmable dividers allow for the following output-to-input frequency ratios: 8:1, 4:1, 2:1, 1:1, 1:2, 1:4, 1:8
- Cycle-to-cycle jitter: 60ps (maximum)
- Output skew: 35ps (maximum)
- Static phase offset: 55ps ± 125ps
- Full 3.3V supply voltage
- 0°C to 70°C ambient operating temperature
- Available in lead-free (RoHS 6) package

Block Diagram



Pin Assignment



8735-31
32-Lead LQFP
7mm x 7mm x 1.4mm package body
Y Package
Top View

Table 1. Pin Descriptions

| Number | Name | Type | | Description |
|-----------------|---------------------------|--------|----------|--|
| 1, 2, 12, 29 | SEL0, SEL1, SEL2, SEL3 | Input | Pulldown | Determines output divider values in Table 3. LVCMOS / LVTTTL interface levels. |
| 3 | CLK0 | Input | Pulldown | Non-inverting differential clock input. |
| 4 | nCLK0 | Input | Pullup | Inverting differential clock input. |
| 5 | CLK1 | Input | Pulldown | Non-inverting differential clock input. |
| 6 | nCLK1 | Input | Pullup | Inverting differential clock input. |
| 7 | CLK_SEL | Input | Pulldown | Clock select input. When HIGH, selects CLK1/nCLK1. When LOW, selects CLK0/nCLK0. LVCMOS / LVTTTL interface levels. |
| 8 | MR | Input | Pulldown | Active HIGH Master Reset. When logic HIGH, the internal dividers are reset causing the true outputs Qx to go low and the inverted outputs nQx to go high. When logic LOW, the internal dividers and the outputs are enabled. LVCMOS / LVTTTL interface levels. |
| 9, 32 | V _{CC} | Power | | Core supply pins. |
| 10 | nFB_IN | Input | Pullup | Inverting differential feedback input to phase detector for regenerating clocks with “zero delay.” |
| 11 | FB_IN | Input | Pulldown | Non-inverted differential feedback input to phase detector for regenerating clocks with “zero delay.” |
| 13, 28 | V _{EE} | Power | | Negative supply pins. |
| 14, 15 | nQ0, Q0 | Output | | Differential output pair. LVPECL interface levels. |
| 16, 17, 24, 25 | V _{CCO} | Power | | Output supply pins. |
| 18, 19 | nQ1, Q1 | Output | | Differential output pair. LVPECL interface levels. |
| 20, 21 | nQ2, Q2 | Output | | Differential output pair. LVPECL interface levels.. |
| 22, 23 | nQ3, Q3 | Output | | Differential output pair. LVPECL interface levels. |
| 26, 27 | nQ4, Q4 | Output | | Differential output pair. LVPECL interface levels. |
| 30 | V _{CCA} | Power | | Analog supply pin. |
| 31 | PLL_SEL | Input | Pullup | PLL select. Selects between the PLL and reference clock as the input to the dividers. When LOW, selects reference clock. When HIGH, selects PLL. LVCMOS/LVTTTL interface levels. |

NOTE: *Pullup* and *Pulldown* refer to internal input resistors. See Table 2, *Pin Characteristics*, for typical values.

Table 2. Pin Characteristics

| Symbol | Parameter | Test Conditions | Minimum | Typical | Maximum | Units |
|-----------------------|-------------------------|-----------------|---------|---------|---------|-------|
| C _{IN} | Input Capacitance | | | 4 | | pF |
| R _{PULLUP} | Input Pullup Resistor | | | 51 | | kΩ |
| R _{PULLDOWN} | Input Pulldown Resistor | | | 51 | | kΩ |

Function Tables

Table 3A. Control Input Function Table

| Inputs | | | | | Outputs PLL_SEL = 1 PLL Enable Mode |
|--------|------|------|------|---------------------------------|---|
| SEL3 | SEL2 | SEL1 | SEL0 | Reference Frequency Range (MHz) | Q0:Q4, nQ0:nQ4 |
| 0 | 0 | 0 | 0 | 125 - 350 | ÷1 |
| 0 | 0 | 0 | 1 | 62.5 - 175 | ÷1 |
| 0 | 0 | 1 | 0 | 31.25 - 87.5 | ÷1 |
| 0 | 0 | 1 | 1 | 15.625 - 43.75 | ÷1 |
| 0 | 1 | 0 | 0 | 125 - 350 | ÷2 |
| 0 | 1 | 0 | 1 | 62.5 - 175 | ÷2 |
| 0 | 1 | 1 | 0 | 31.25 - 87.5 | ÷2 |
| 0 | 1 | 1 | 1 | 125 - 350 | ÷4 |
| 1 | 0 | 0 | 0 | 62.5 - 175 | ÷4 |
| 1 | 0 | 0 | 1 | 125 - 350 | ÷8 |
| 1 | 0 | 1 | 0 | 62.5 - 175 | x2 |
| 1 | 0 | 1 | 1 | 31.25 - 87.5 | x2 |
| 1 | 1 | 0 | 0 | 15.625 - 43.75 | x2 |
| 1 | 1 | 0 | 1 | 31.25 - 87.5 | x4 |
| 1 | 1 | 1 | 0 | 15.625 - 43.75 | x4 |
| 1 | 1 | 1 | 1 | 15.625 - 43.75 | x8 |

Table 3B. PLL Bypass Function Table

| Inputs | | | | Outputs PLL_SEL = 0 PLL Bypass Mode |
|--------|------|------|------|---|
| SEL3 | SEL2 | SEL1 | SEL0 | Q0:Q4, nQ0:nQ4 |
| 0 | 0 | 0 | 0 | ÷8 |
| 0 | 0 | 0 | 1 | ÷8 |
| 0 | 0 | 1 | 0 | ÷8 |
| 0 | 0 | 1 | 1 | ÷16 |
| 0 | 1 | 0 | 0 | ÷16 |
| 0 | 1 | 0 | 1 | ÷16 |
| 0 | 1 | 1 | 0 | ÷32 |
| 0 | 1 | 1 | 1 | ÷32 |
| 1 | 0 | 0 | 0 | ÷64 |
| 1 | 0 | 0 | 1 | ÷128 |
| 1 | 0 | 1 | 0 | ÷4 |
| 1 | 0 | 1 | 1 | ÷4 |
| 1 | 1 | 0 | 0 | ÷8 |
| 1 | 1 | 0 | 1 | ÷2 |
| 1 | 1 | 1 | 0 | ÷4 |
| 1 | 1 | 1 | 1 | ÷2 |

Absolute Maximum Ratings

NOTE: Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics* or *AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

| Item | Rating |
|---|--------------------------|
| Supply Voltage, V_{CC} | 4.6V |
| Inputs, V_I | -0.5V to $V_{CC} + 0.5V$ |
| Outputs, I_O Continuous Current Surge Current | 50mA 100mA |
| Package Thermal Impedance, θ_{JA} | 47.9°C/W (0 lfpm) |
| Storage Temperature, T_{STG} | -65°C to 150°C |

DC Electrical Characteristics

Table 4A. Power Supply DC Characteristics, $V_{CC} = V_{CCA} = V_{CCO} = 3.3V \pm 5\%$, $V_{EE} = 0V$, $T_A = 0^\circ C$ to $70^\circ C$

| Symbol | Parameter | Test Conditions | Minimum | Typical | Maximum | Units |
|-----------|-----------------------|-----------------|---------|---------|---------|-------|
| V_{CC} | Core Supply Voltage | | 3.135 | 3.3 | 3.465 | V |
| V_{CCA} | Analog Supply Voltage | | 3.135 | 3.3 | 3.465 | V |
| V_{CCO} | Output Supply Voltage | | 3.135 | 3.3 | 3.465 | V |
| I_{EE} | Power Supply Current | | | | 150 | mA |
| I_{CCA} | Analog Supply Current | | | | 15 | mA |

Table 4B. LVCMOS/LVTTL DC Characteristics, $V_{CC} = V_{CCA} = V_{CCO} = 3.3V \pm 5\%$, $V_{EE} = 0V$, $T_A = 0^\circ C$ to $70^\circ C$

| Symbol | Parameter | Test Conditions | Minimum | Typical | Maximum | Units |
|----------|--------------------|--------------------------|--------------------------------|---------|----------------|---------|
| V_{IH} | Input High Voltage | | 2 | | $V_{CC} + 0.3$ | V |
| V_{IL} | Input Low Voltage | | -0.3 | | 0.8 | V |
| I_{IH} | Input High Current | CLK_SEL, SEL[0:3], MR | $V_{CC} = V_{IN} = 3.465V$ | | 150 | μA |
| | | PLL_SEL | $V_{CC} = V_{IN} = 3.465V$ | | 5 | μA |
| I_{IL} | Input Low Current | CLK_SEL, SEL[0:3], MR | $V_{CC} = 3.465V, V_{IN} = 0V$ | -5 | | μA |
| | | PLL_SEL | $V_{CC} = 3.465V, V_{IN} = 0V$ | -150 | | μA |

Table 4C. Differential DC Characteristics, $V_{CC} = V_{CCA} = V_{CCO} = 3.3V \pm 5\%$, $V_{EE} = 0V$, $T_A = 0^\circ C$ to $70^\circ C$

| Symbol | Parameter | Test Conditions | Minimum | Typical | Maximum | Units |
|-----------|--------------------------------------|----------------------|--------------------------------------|---------|-----------------|---------|
| I_{IH} | Input High Current | FB_IN, CLK0, CLK1 | $V_{CC} = V_{IN} = 3.465V$ | | 150 | μA |
| | | nFB_IN, nCLK0, nCLK1 | $V_{CC} = V_{IN} = 3.465V$ | | 5 | μA |
| I_{IL} | Input Low Current | FB_IN, CLK0, CLK1 | $V_{CC} = 3.465V$, $V_{IN} = 0V$ | -5 | | μA |
| | | nFB_IN, nCLK0, nCLK1 | $V_{CC} = 3.465V$, $V_{IN} = 0V$ | -150 | | μA |
| V_{PP} | Peak-to-Peak Voltage; NOTE 1 | | 0.15 | | 1.3 | V |
| V_{CMR} | Common Mode Input Voltage; NOTE 1, 2 | | $V_{EE} + 0.5$ | | $V_{CC} - 0.85$ | V |

 NOTE 1: V_{IL} should not be less than $-0.3V$.

 NOTE 2: Common mode input voltage is defined as V_{IH} .

Table 4D. LVPECL DC Characteristics, $V_{CC} = V_{CCA} = V_{CCO} = 3.3V \pm 5\%$, $V_{EE} = 0V$, $T_A = 0^\circ C$ to $70^\circ C$

| Symbol | Parameter | Test Conditions | Minimum | Typical | Maximum | Units |
|-------------|-----------------------------------|-----------------|-----------------|---------|-----------------|-------|
| V_{OH} | Output High Voltage; NOTE 1 | | $V_{CCO} - 1.4$ | | $V_{CCO} - 0.9$ | V |
| V_{OL} | Output Low Voltage; NOTE 1 | | $V_{CCO} - 2.0$ | | $V_{CCO} - 1.7$ | V |
| V_{SWING} | Peak-to-Peak Output Voltage Swing | | 0.6 | | 1.0 | V |

 NOTE 1: Outputs terminated with 50Ω to $V_{CCO} - 2V$.

Table 5. Input Frequency Characteristics, $V_{CC} = V_{CCA} = V_{CCO} = 3.3V \pm 5\%$, $V_{EE} = 0V$, $T_A = 0^\circ C$ to $70^\circ C$

| Symbol | Parameter | Test Conditions | Minimum | Typical | Maximum | Units |
|----------|-----------------|------------------------|-------------|---------|---------|-------|
| f_{IN} | Input Frequency | CLK0/nCLK0, CLK1/nCLK1 | PLL_SEL = 1 | 15.625 | 350 | MHz |
| | | | PLL_SEL = 0 | | 700 | MHz |

AC Electrical Characteristics

Table 6. AC Characteristics, $V_{CC} = V_{CCA} = V_{CCO} = 3.3V \pm 5\%$, $V_{EE} = 0V$, $T_A = 0^\circ C$ to $70^\circ C$

| Symbol | Parameter | Test Conditions | Minimum | Typical | Maximum | Units |
|---------------------|--------------------------------|------------------------------|---------|---------|---------|-------|
| f_{MAX} | Output Frequency | | | | 350 | MHz |
| t_{PD} | Propagation Delay; NOTE 1 | PLL_SEL = 0, $f \leq 350MHz$ | 3.8 | | 5.1 | ns |
| $t_{sk(o)}$ | Output Skew; NOTE 2, 3 | | | | 35 | ps |
| $t_{sk(\emptyset)}$ | Static Phase Offset; NOTE 3, 4 | PLL_SEL = 1 | -70 | 55 | +180 | ps |
| $f_{jit(cc)}$ | Cycle-to-Cycle Jitter; NOTE 3 | | | | 60 | ps |
| t_L | PLL Lock Time | | | | 1 | ms |
| t_R / t_F | Output Rise/Fall Time | 20% to 80% | 200 | | 750 | ps |
| odc | Output Duty Cycle | | 47 | | 53 | % |

NOTE: Electrical parameters are guaranteed over the specified ambient operating temperature range, which is established when the device is mounted in a test socket with maintained transverse airflow greater than 500 lfpm. The device will meet specifications after thermal equilibrium has been reached under these conditions.

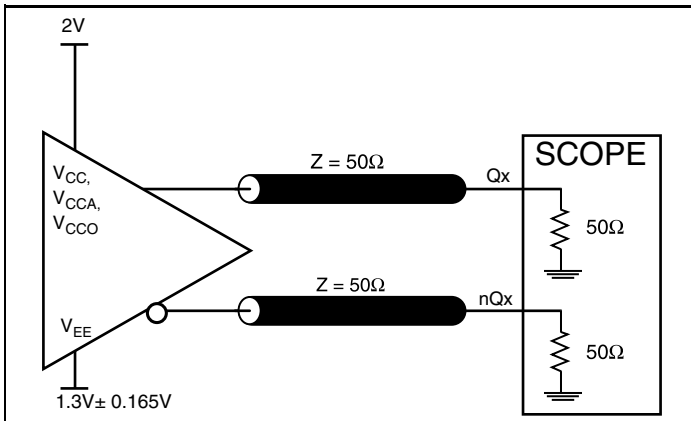
NOTE 1: Measured from the differential input crossing point to the differential output crossing point.

NOTE 2: Defined as skew between outputs at the same supply voltage and with equal load conditions. Measured at the output differential cross points.

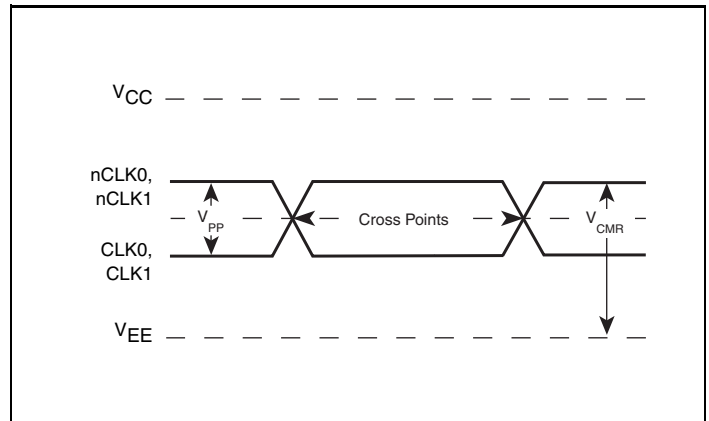
NOTE 3: This parameter is defined in accordance with JEDEC Standard 65.

NOTE 4: Defined as the time difference between the input reference clock and the averaged feedback input signal across all conditions, when the PLL is locked and the input reference frequency is stable.

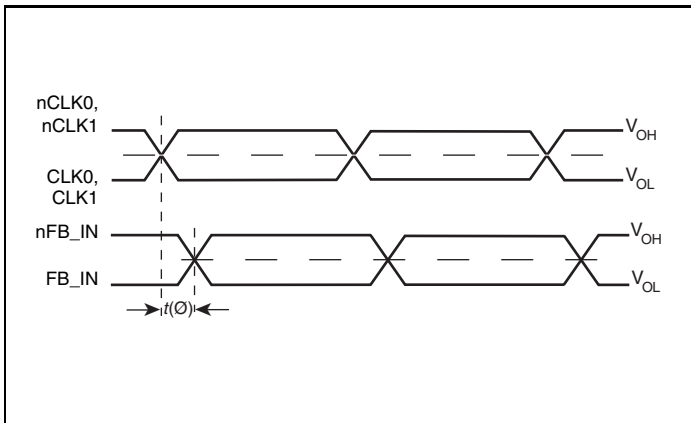
Parameter Measurement Information



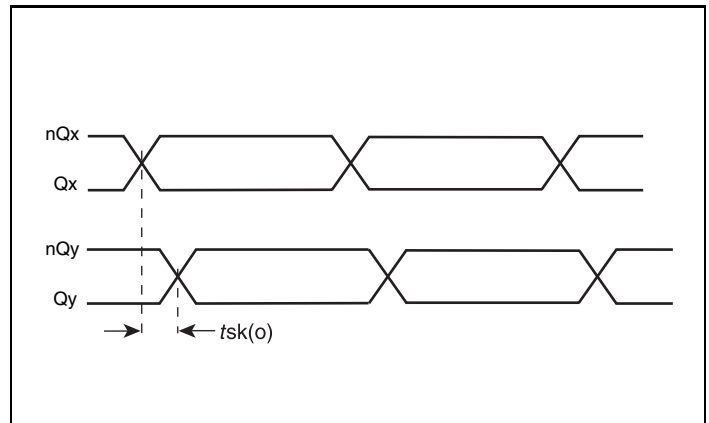
3.3V Output Load AC Test Circuit



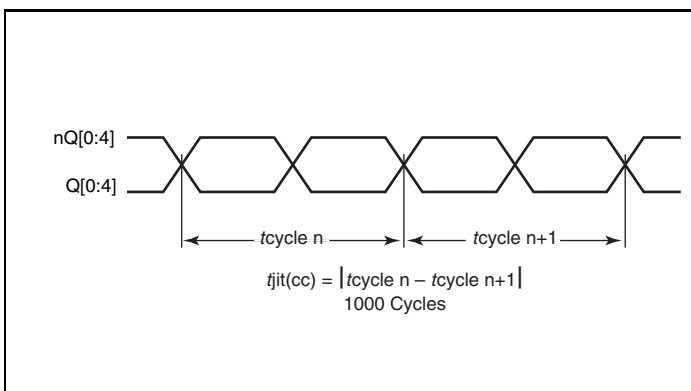
Differential Input Level



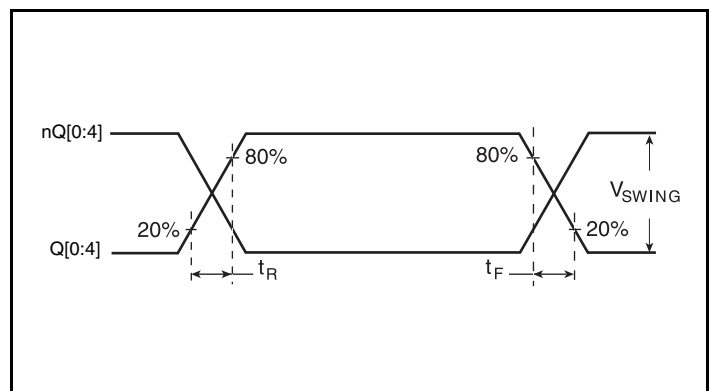
Phase Jitter and Static Phase Offset



Output Skew

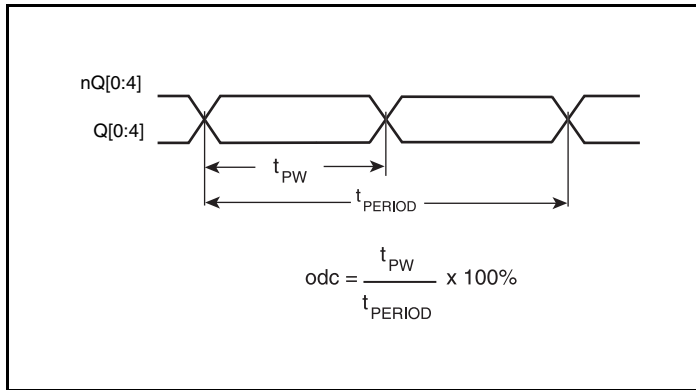


Cycle-to-Cycle Jitter

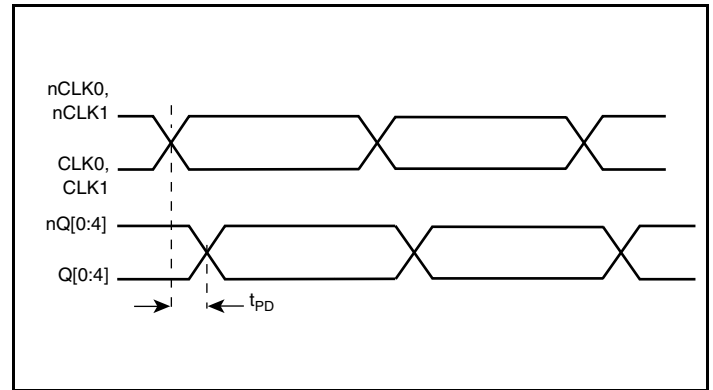


Output Rise/Fall Time

Parameter Measurement Information, continued



Output Duty Cycle/Pulse Width/Period



Propagation Delay

Application Information

Recommendations for Unused Input and Output Pins

Inputs:

LVC MOS Control Pins

All control pins have internal pullups or pulldowns; additional resistance is not required but can be added for additional protection. A 1kΩ resistor can be used.

CLK/nCLK Inputs

For applications not requiring the use of the differential input, both CLK and nCLK can be left floating. Though not required, but for additional protection, a 1kΩ resistor can be tied from CLK to ground.

FB_IN/nFB_IN Inputs

For applications not requiring the use of the differential input, both FB_IN and nFB_IN can be left floating. Though not required, but for additional protection, a 1kΩ resistor can be tied from FB_IN to ground.

Outputs:

LVPECL Outputs

All unused LVPECL outputs can be left floating. We recommend that there is no trace attached. Both sides of the differential output pair should either be left floating or terminated.

Power Supply Filtering Technique

As in any high speed analog circuitry, the power supply pins are vulnerable to random noise. To achieve optimum jitter performance, power supply isolation is required. The 8735-31 provides separate power supplies to isolate any high switching noise from the outputs to the internal PLL. V_{CC} , V_{CCA} and V_{CCO} should be individually connected to the power supply plane through vias, and $0.01\mu\text{F}$ bypass capacitors should be used for each pin. *Figure 1* illustrates this for a generic V_{CC} pin and also shows that V_{CCA} requires that an additional 10Ω resistor along with a $10\mu\text{F}$ bypass capacitor be connected to the V_{CCA} pin. The 10Ω resistor can also be replaced by a ferrite bead.

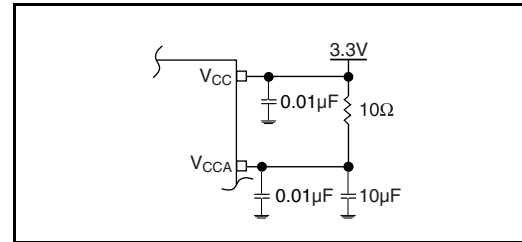


Figure 1. Power Supply Filtering

Wiring the Differential Input to Accept Single Ended Levels

Figure 2 shows how the differential input can be wired to accept single ended levels. The reference voltage $V_{REF} = V_{CC}/2$ is generated by the bias resistors $R1$, $R2$ and $C1$. This bias circuit should be located as close as possible to the input pin. The ratio of $R1$ and $R2$ might need to be adjusted to position the V_{REF} in the center of the input voltage swing. For example, if the input clock swing is only 2.5V and $V_{CC} = 3.3\text{V}$, V_{REF} should be 1.25V and $R2/R1 = 0.609$.

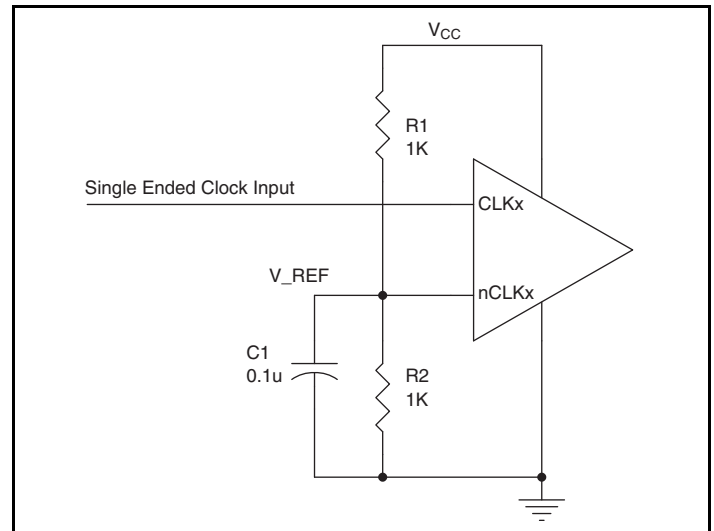


Figure 2. Single-Ended Signal Driving Differential Input

Differential Clock Input Interface

The CLK /nCLK accepts LVDS, LVPECL, LVHSTL, SSTL, HCSL and other differential signals. Both V_{SWING} and V_{OH} must meet the V_{PP} and V_{CMR} input requirements. Figures 3A to 3F show interface examples for the HiPerClockS CLK/nCLK input driven by the most common driver types. The input interfaces suggested here are examples only. Please consult with the vendor of the driver

component to confirm the driver termination requirements. For example, in Figure 3A, the input termination applies for IDT HiPerClockS open emitter LVHSTL drivers. If you are using an LVHSTL driver from another vendor, use their termination recommendation.

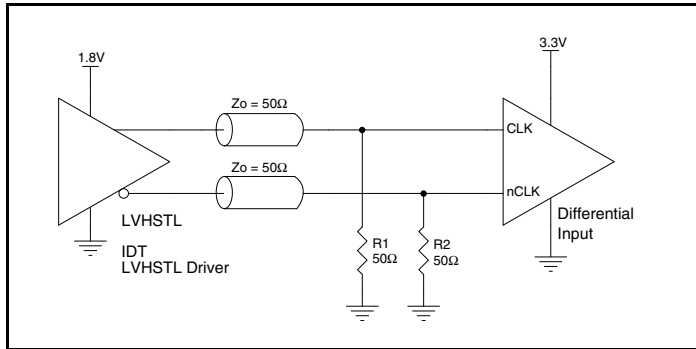


Figure 3A. HiPerClockS CLK/nCLK Input Driven by an IDT Open Emitter HiPerClockS LVHSTL Driver

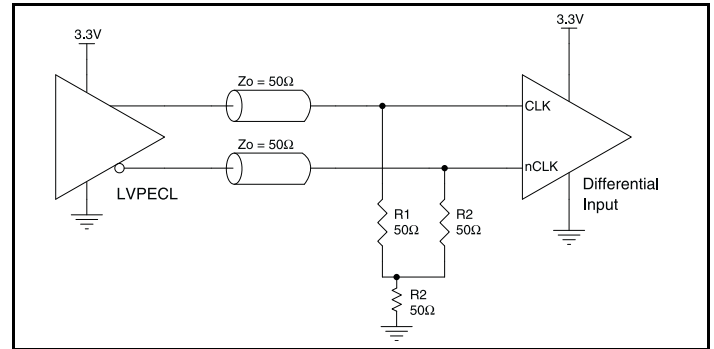


Figure 3B. HiPerClockS CLK/nCLK Input Driven by a 3.3V LVPECL Driver

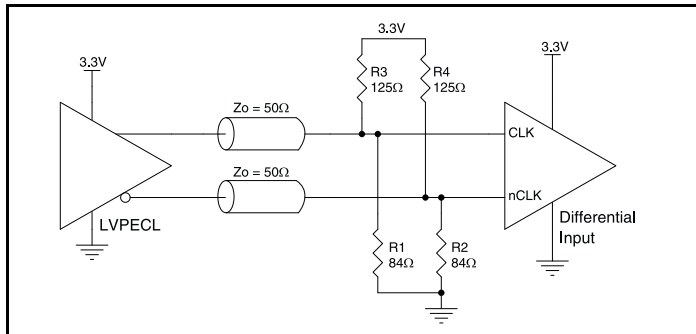


Figure 3C. HiPerClockS CLK/nCLK Input Driven by a 3.3V LVPECL Driver

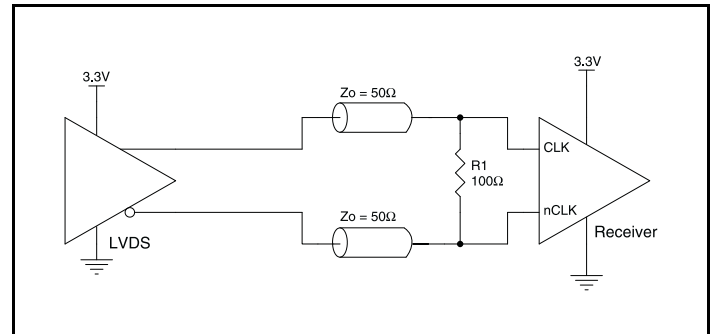


Figure 3D. HiPerClockS CLK/nCLK Input Driven by a 3.3V LVDS Driver

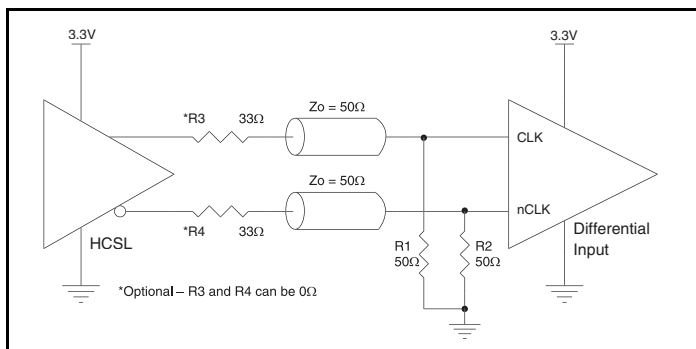


Figure 3E. HiPerClockS CLK/nCLK Input Driven by a 3.3V HCSL Driver

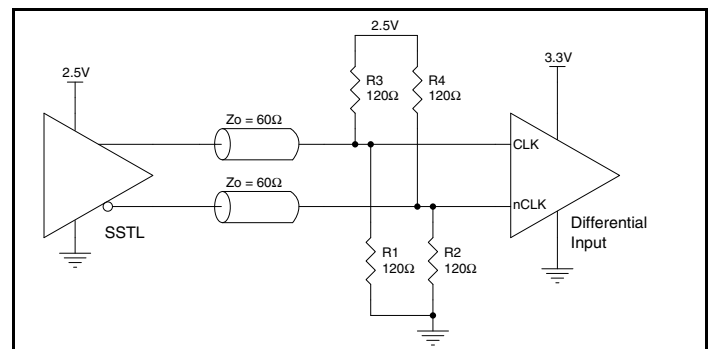


Figure 3F. HiPerClockS CLK/nCLK Input Driven by a 2.5V SSTL Driver

Termination for 3.3V LVPECL Outputs

The clock layout topology shown below is a typical termination for LVPECL outputs. The two different layouts mentioned are recommended only as guidelines.

FOUT and nFOUT are low impedance follower outputs that generate ECL/LVPECL compatible outputs. Therefore, terminating resistors (DC current path to ground) or current sources must be used for functionality. These outputs are designed to drive 50Ω

transmission lines. Matched impedance techniques should be used to maximize operating frequency and minimize signal distortion. *Figures 4A and 4B* show two different layouts which are recommended only as guidelines. Other suitable clock layouts may exist and it would be recommended that the board designers simulate to guarantee compatibility across all printed circuit and clock component process variations.

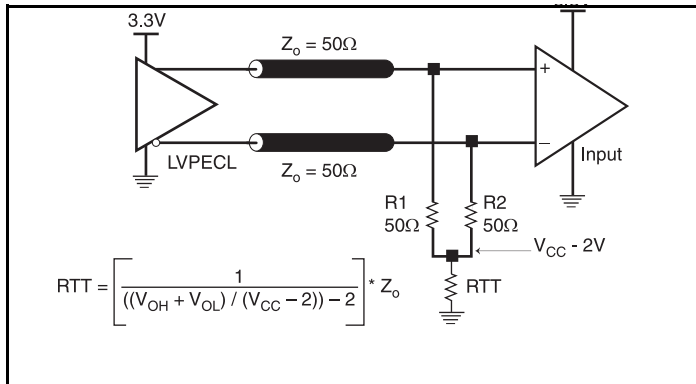


Figure 4A. 3.3V LVPECL Output Termination

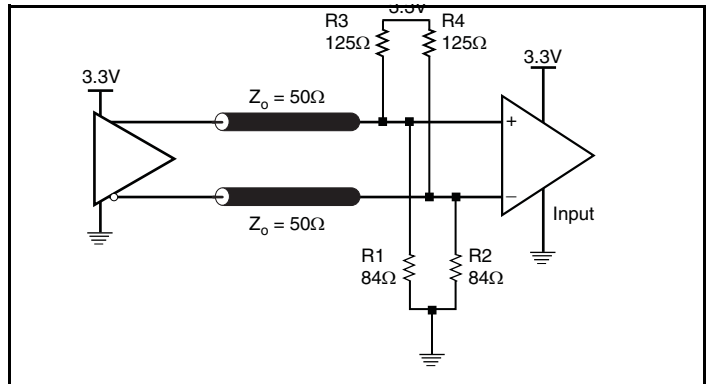


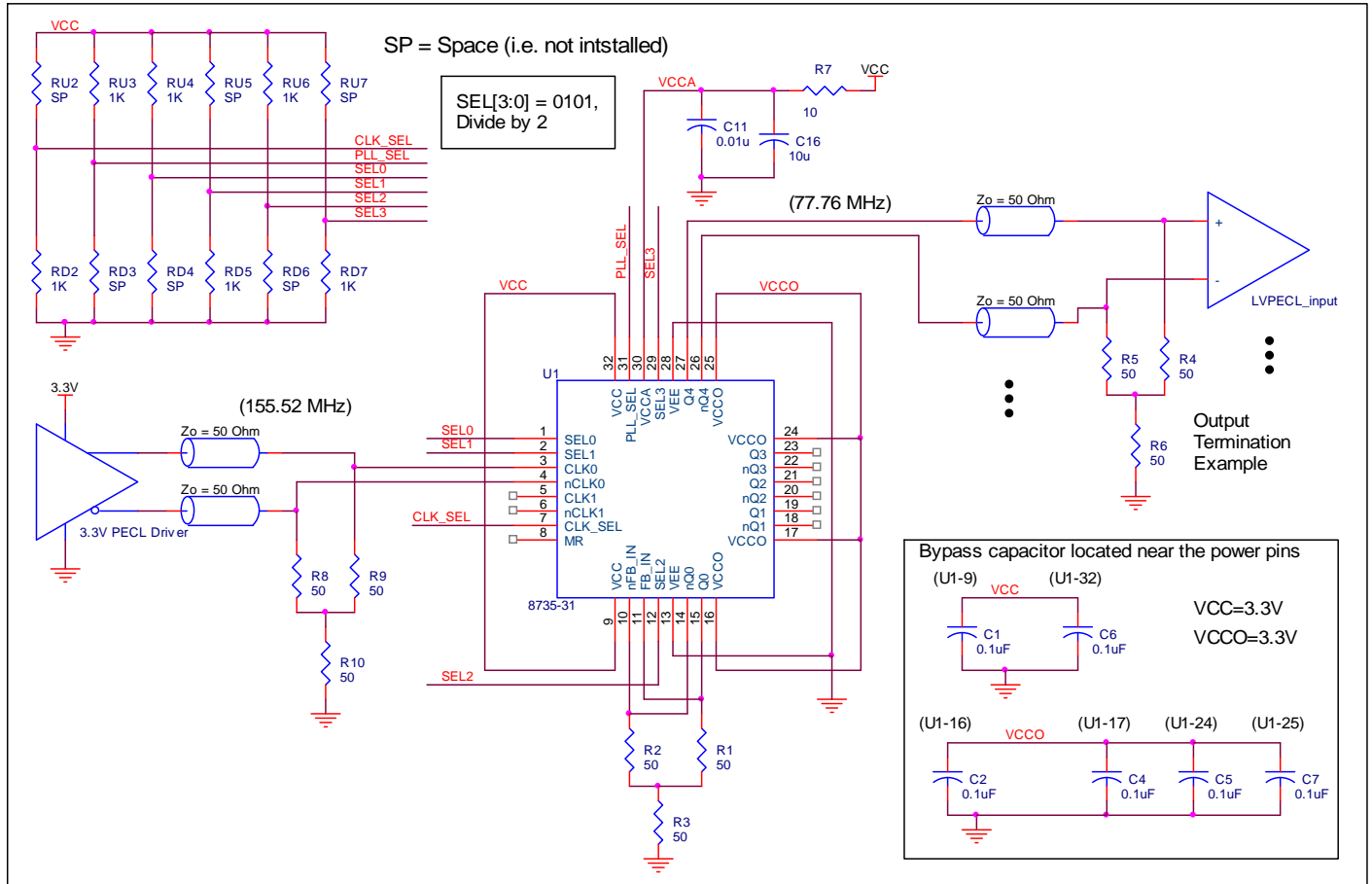
Figure 4B. 3.3V LVPECL Output Termination

Layout Guideline

The schematic of the 8735-31 layout example is shown in *Figure 5A*. The 8735-31 recommended PCB board layout for this example is shown in *Figure 5B*. This layout example is used as a general

guideline. The layout in the actual system will depend on the selected component types, the density of the components, the density of the traces, and the stacking of the P.C. board.

Figure 5A. 8735-31 LVPECL Zero Delay Buffer Schematic Example



The following component footprints are used in this layout example. All the resistors and capacitors are size 0603.

Power and Grounding

Place the decoupling capacitors C1, C6, C2, C4, C5, and C7, as close as possible to the power pins. If space allows, placement of the decoupling capacitor on the component side is preferred. This can reduce unwanted inductance between the decoupling capacitor and the power pin caused by the via.

Maximize the power and ground pad sizes and number of vias capacitors. This can reduce the inductance between the power and ground planes and the component power and ground pins.

The RC filter consisting of R7, C11, and C16 should be placed as close to the V_{CCA} pin as possible.

Clock Traces and Termination

Poor signal integrity can degrade the system performance or cause system failure. In synchronous high-speed digital systems, the clock signal is less tolerant to poor signal integrity than other signals. Any ringing on the rising or falling edge or excessive ring back can cause system failure. The shape of the trace and the trace delay might be restricted by the available space on the board and the component location. While routing the traces, the

clock signal traces should be routed first and should be locked prior to routing other signal traces.

- The differential 50Ω output traces should have the same length.
- Avoid sharp angles on the clock trace. Sharp angle turns cause the characteristic impedance to change on the transmission lines.
- Keep the clock traces on the same layer. Whenever possible, avoid placing vias on the clock traces. Placement of vias on the traces can affect the trace characteristic impedance and hence degrade signal integrity.
- To prevent cross talk, avoid routing other signal traces in parallel with the clock traces. If running parallel traces is unavoidable, allow a separation of at least three trace widths between the differential clock trace and the other signal trace.
- Make sure no other signal traces are routed between the clock trace pair.
- The matching termination resistors should be located as close to the receiver input pins as possible.

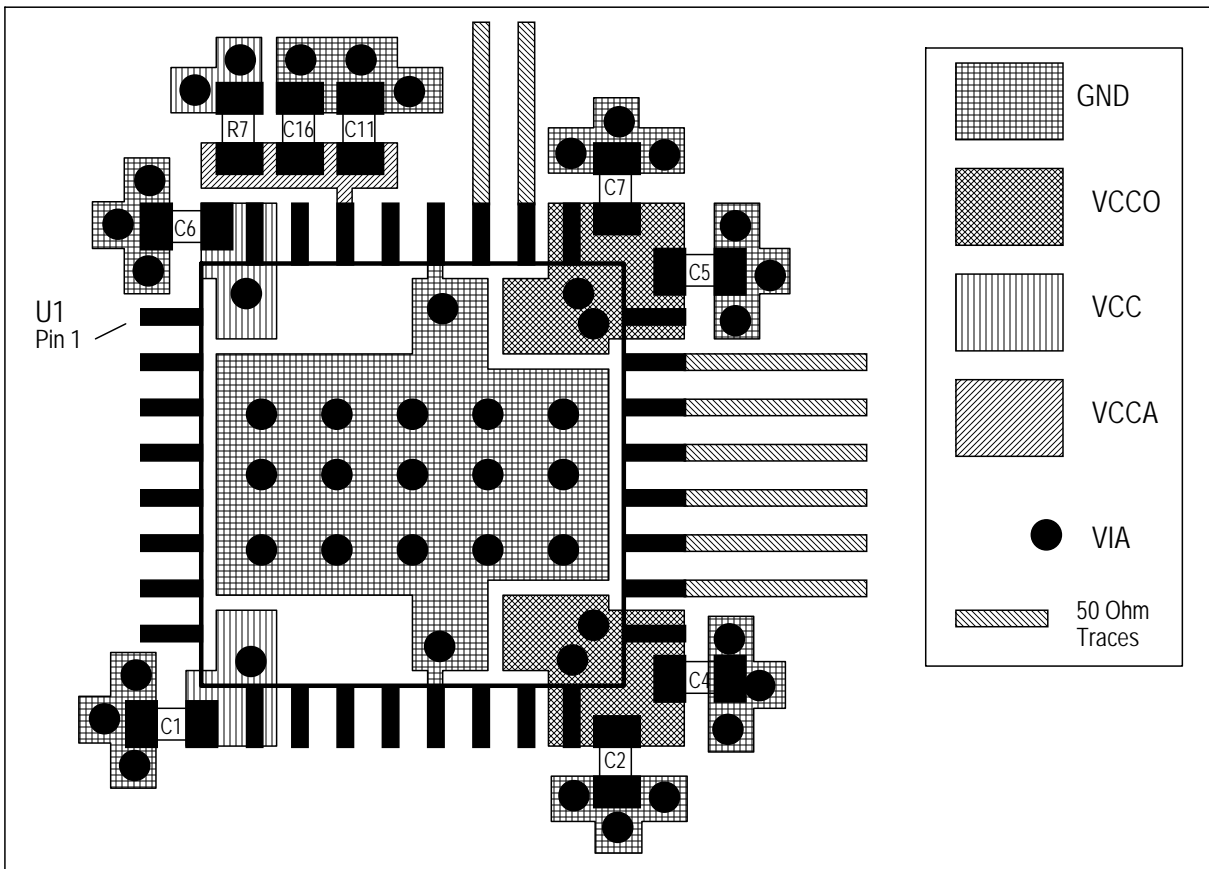


Figure 5B. PCB Board Layout for 8735-31

Power Considerations

This section provides information on power dissipation and junction temperature for the 8735-31. Equations and example calculations are also provided.

1. Power Dissipation.

The total power dissipation for the 8735-31 is the sum of the core power plus the power dissipated in the load(s). The following is the power dissipation for $V_{CC} = 3.3V + 5\% = 3.465V$, which gives worst case results.

NOTE: Please refer to Section 3 for details on calculating power dissipated in the load.

- Power (core)_{MAX} = $V_{CC_MAX} * I_{CC_MAX} = 3.465V * 150mA = \mathbf{519.75mW}$
- Power (outputs)_{MAX} = **30mW/Loaded output pair**
If all outputs are loaded, the total power is $5 * 30mW = \mathbf{150mW}$

Total Power_{MAX} = (3.465V, with all outputs switching) = $519.75mW + 150mW = \mathbf{669.75mW}$

2. Junction Temperature.

Junction temperature, T_j , is the temperature at the junction of the bond wire and bond pad and directly affects the reliability of the device. The maximum recommended junction temperature for HiPerClockS devices is 125°C.

The equation for T_j is as follows: $T_j = \theta_{JA} * Pd_total + T_A$

T_j = Junction Temperature

θ_{JA} = Junction-to-Ambient Thermal Resistance

Pd_total = Total Device Power Dissipation (example calculation is in section 1 above)

T_A = Ambient Temperature

In order to calculate junction temperature, the appropriate junction-to-ambient thermal resistance θ_{JA} must be used. Assuming no air flow and a multi-layer board, the appropriate value is 42.1°C/W per Table 7 below.

Therefore, T_j for an ambient temperature of 70°C with all outputs switching is:

$70^\circ C + 0.670W * 42.1^\circ C/W = 98.2^\circ C$. This is well below the limit of 125°C.

This calculation is only an example. T_j will obviously vary depending on the number of loaded outputs, supply voltage, air flow and the type of board (multi-layer).

Table 7. Thermal Resistance θ_{JA} for 32 Lead LQFP, Forced Convection

| Linear Feet per Minute | θ_{JA} vs. Air Flow | | |
|--|----------------------------|----------|----------|
| | 0 | 200 | 500 |
| Single-Layer PCB, JEDEC Standard Test Boards | 67.8°C/W | 55.9°C/W | 50.1°C/W |
| Multi-Layer PCB, JEDEC Standard Test Boards | 47.9°C/W | 42.1°C/W | 39.4°C/W |

NOTE: Most modern PCB designs use multi-layered boards. The data in the second row pertains to most designs.

3. Calculations and Equations.

The purpose of this section is to derive the power dissipated into the load.

LVPECL output driver circuit and termination are shown in *Figure 6*.

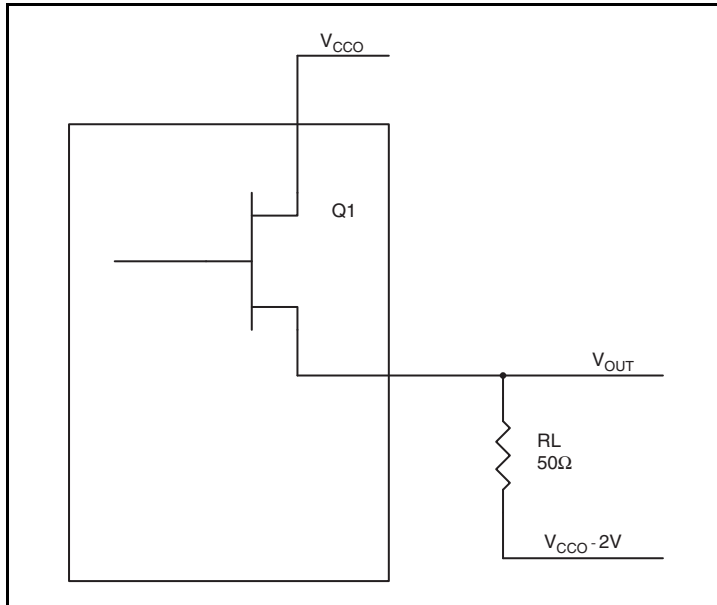


Figure 6. LVPECL Driver Circuit and Termination

To calculate worst case power dissipation into the load, use the following equations which assume a 50Ω load, and a termination voltage of $V_{CCO} - 2V$.

- For logic high, $V_{OUT} = V_{OH_MAX} = V_{CCO_MAX} - 0.9V$
 $(V_{CCO_MAX} - V_{OH_MAX}) = 0.9V$
- For logic low, $V_{OUT} = V_{OL_MAX} = V_{CCO_MAX} - 1.7V$
 $(V_{CCO_MAX} - V_{OL_MAX}) = 1.7V$

Pd_H is power dissipation when the output drives high.

Pd_L is the power dissipation when the output drives low.

$$Pd_H = [(V_{OH_MAX} - (V_{CCO_MAX} - 2V))/R_L] * (V_{CCO_MAX} - V_{OH_MAX}) = [(2V - (V_{CCO_MAX} - V_{OH_MAX}))/R_L] * (V_{CCO_MAX} - V_{OH_MAX}) = [(2V - 0.9V)/50\Omega] * 0.9V = \mathbf{19.8mW}$$

$$Pd_L = [(V_{OL_MAX} - (V_{CCO_MAX} - 2V))/R_L] * (V_{CCO_MAX} - V_{OL_MAX}) = [(2V - (V_{CCO_MAX} - V_{OL_MAX}))/R_L] * (V_{CCO_MAX} - V_{OL_MAX}) = [(2V - 1.7V)/50\Omega] * 1.7V = \mathbf{10.2mW}$$

$$\text{Total Power Dissipation per output pair} = Pd_H + Pd_L = \mathbf{30mW}$$

Reliability Information

Table 8. θ_{JA} vs. Air Flow Table for a 32 Lead LQFP

| θ_{JA} vs. Air Flow | | | |
|--|----------|----------|----------|
| Linear Feet per Minute | 0 | 200 | 500 |
| Single-Layer PCB, JEDEC Standard Test Boards | 67.8°C/W | 55.9°C/W | 50.1°C/W |
| Multi-Layer PCB, JEDEC Standard Test Boards | 47.9°C/W | 42.1°C/W | 39.4°C/W |
| NOTE: Most modern PCB designs use multi-layered boards. The data in the second row pertains to most designs. | | | |

Transistor Count

The transistor count for 8735-31 is: 2969

Package Outline and Package Dimensions

Package Outline - M Suffix for 32 Lead LQFP

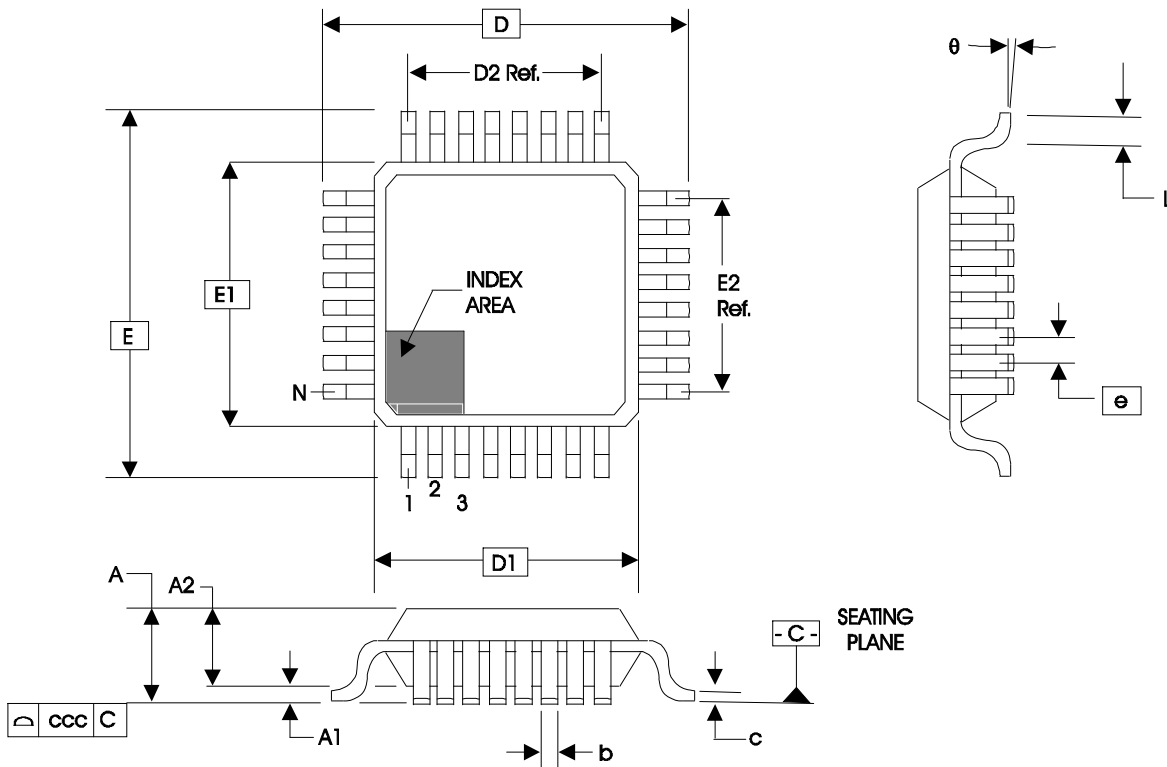


Table 6. Package Dimensions for 32 Lead LQFP

| JEDEC Variation: BBC - HD | | | |
|-------------------------------|------------|---------|---------|
| All Dimensions in Millimeters | | | |
| Symbol | Minimum | Nominal | Maximum |
| N | 32 | | |
| A | | | 1.60 |
| A1 | 0.05 | 0.10 | 0.15 |
| A2 | 1.35 | 1.40 | 1.45 |
| b | 0.30 | 0.37 | 0.45 |
| c | 0.09 | | 0.20 |
| D & E | 9.00 Basic | | |
| D1 & E1 | 7.00 Basic | | |
| D2 & E2 | 5.60 Ref. | | |
| e | 0.80 Basic | | |
| L | 0.45 | 0.60 | 0.75 |
| θ | 0° | | 7° |
| ccc | | | 0.10 |

Reference Document: JEDEC Publication 95, MS-026

Ordering Information

Table 10. Ordering Information

| Part/Order Number | Marking | Package | Shipping Packaging | Temperature |
|--------------------------|----------------|--------------------------|---------------------------|--------------------|
| 8735AY-31LF | ICS8735AY31LF | "Lead-Free" 32 Lead LQFP | Tray | 0°C to 70°C |
| 8735AY-31LFT | ICS8735AY31LF | "Lead-Free" 32 Lead LQFP | Tape & Reel | 0°C to 70°C |

Revision History Sheet

| Rev | Table | Page | Description of Change | Date |
|-----|-------|---------------|--|----------|
| A | T10 | 16 | Ordering Information Table - added Lead-Free marking. | 12/19/07 |
| A | T10 | 9 11 19 | Added <i>Recommendations for Unused Input and Output Pins</i> section. Updated <i>Differential Clock input Interface</i> section. Ordering Information Table - deleted "ICS" from Part/Order Number. | 2/11/08 |
| B | | 1 | Pin Assignment -due to format conversion dated February 11, 2008 datasheet, corrected typo on pin 19 from nQ1 to Q1 and, pin 10 from FB_IN to nFB_IN. | 2/18/09 |
| B | T10 | 19 | Ordering Information - removed leaded devices. Updated datasheet format. | 7/16/15 |
| B | T10 | 1 19 | Features Section - removed reference to leaded packages. Ordering Information - Deleted LF note below table. Updated header and footer. | 1/27/16 |



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